



#### Figure 1 : TE-XC3S Spartan-3 Micromodule Features

- High-density plug-in Spartan-3 module
- USB 2.0 interface
- Platform Flash for in-system configuration
- 64kBit serial EEPROM
- Power supply via USB or external 5 Volt input
- Low cost and flexible
- Multiple Micromodules are stackable
- Flexible expansion via high-density board connectors

# **Applications**

- USB 2.0 Device development
- IP development
- Digital signal processing
- General-purpose prototyping platform
- Retro-computing system platform

#### Introduction

The TE-XC3S is a development platform based on Xilinx Spartan-3 FPGA. The small size and it's high-density connectors are designed as a ready-to-use plug-in module for carrier boards. The tiny 2 x 1.7 inch module integrates perfectly in battery-powered, handheld or USB-powered applications.

Also available from Trenz Electronic are several carrier boards, eg. for retro computing and emulation of popular arcade games or home computers.

# **Specifications**

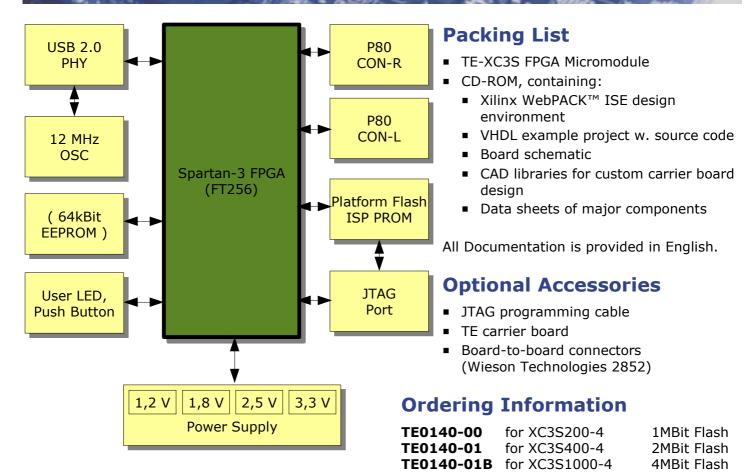
	TE-XC3S	
Xilinx Spartan-3 FPGA	XC3S200-4FT256C	Rev. 00
	XC3S400-4FT256C	Rev. 01
	XC3S1000-4FT256C	
Configuration	Xilinx XCF01, XCF02 or XCF04 Platform Flash	
USB	USB 2.0 GT3200 PHY	
EEPROM	64kBit serial (only Rev. 01)	
Buttons / Signals	1 LED, 1 push button	
Clock	30MHz or 60MHz via USB PHY	
Power supply	5 Volt input (or USB-powered)	
External connectors	2 x 80 pin high-density board-to- board connectors	
Dimensions	50,7 x 43,6 mm (2,0 x 1,7 inch)	



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# FPGA DEVELOPMEN SYSTEMS



# **Bundled Software**

- Xilinx ISE WebPACK<sup>™</sup> FPGA design environment, including design entry, simulation and synthesis
- Example VHDL design
- All documentation is provided in English.

#### **Local Contact**

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